

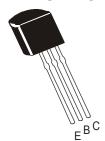
Continental Device India Limited

An ISO/TS 16949, ISO 9001 and ISO 14001 Certified Company





PNP SILICON PLANAR AMPLIFIER TRANSISTORS



MPS8598 MPS8599

TO-92 Plastic Package

ABSOLUTE MAXIMUM RATINGS(T_a=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	MPS8598	MPS8599	UNITS	
Collector Emitter Voltage	$V_{\sf CEO}$	60	80	V	
Collector Base Voltage	V_{CBO}	60	80	V	
Emitter Base Voltage	V_{EBO}	5	5	V	
Collector Current Continuous	I _C	I _C 500		mA	
Power Dissipation @ T _a =25°C	P_{D}	625		mW	
Derate Above 25°C		5	5.0	mW/ ºC	
Power Dissipation @ T _c =25°C	P_{D}	1	1.5		
Derate Above 25°C		12		mW/ °C	
Operating And Storage Junction Temperature Range	T_{j},T_{stg}	-55 to +150		°C	
THERMAL RESISTANCE					
Junction to Ambient in free air	$R_{th(j-a)}$	2	00	°C/W	
Junction to Case in free air	R _{th(j-c)}	8	3.3	°C/W	

ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
Collector Emitter Breakdow Voltage	BV _{CEO}	$I_C=10$ mA, $I_B=0$			
MPS8598			60		V
MPS8599			80		V
Collector Base Voltage	BV_CBO	$I_C=100\mu A, I_E=0$			
MPS8598			60		V
MPS8599			80		V
Emitter Base Voltage	BV_{EBO}	$I_E=10\mu A, I_C=0$	5		V
Collector Cutoff Current	I _{CEO}			100	nA
Collector Cutoff Current	I _{CBO}				
MPS8598		$V_{CE}=60V$, $I_{E}=0$		100	nA
MPS8599				100	nA
Emitter Cut off Current	I _{EBO}	$V_{BE}=4V, I_C=0$			
DC Current Gain					
	h _{FE}	V _{CE} =5V,I _C =1mA	100	300	
		$V_{CE}=5V,I_{C}=10mA$	100		
_	_	V _{CE} =5V,I _C =100mA*	75		

^{*}Pulse Condition: = Width < 300ms, Duty Cycle < 2%.

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ELECTRICAL CHARACTERISTICS (T_a=25°C unless specified otherwise)

DESCRIPTION	SYMBOL	TEST CONDITION	MIN	MAX	UNITS
Collector Emitter Saturation Voltage	V _{CE (sat)} *	$I_C=100$ ma, $I_B=5$ mA		0.4	V
		$I_C=100$ ma, $I_B=10$ mA		0.3	V
Base Emitter on Voltage	V _{BE (on)}				
MPS8598		$I_C=1$ mA, $V_{CE}=5$ V	0.5	0.7	V
MPS8599		I _C =10mA, V _{CE} =5V	0.6	0.8	V

DYNAMIC CHARACTERISTICS

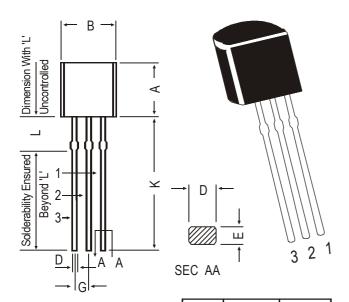
Transition Frequency	f _T	I _C =10mA, V _{CE} =5V			
		f=100MHz	150		MHz
Output Capacitance	C_ob	$I_E=0, V_{CB}=5V$			
		f=1MHz		8	pF
Input Capacitance	C_{ib}	Ic=0, V _{EB} =0.5V			
		f=1MHz		30	pF

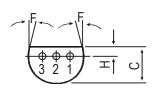
^{*}Pulse Condition: = Width \leq 300ms, Duty Cycle \leq 2%.

TO-92 Plastic Package

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TO-92 Transistors in Tape and Ammo Pack





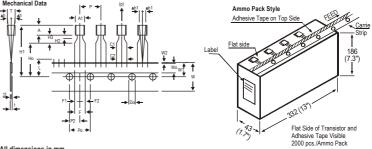
PIN CONFIGURATION

1. COLLECTOR 2. BASE

3. EMITTER

DIM MIN. MAX. 4.32 5.33 В 4.45 5.20 С 4.19 3.18 D 0.41 0.55 Ε 0.35 0.50 F 5 DEG G 1.14 1.40 1.53 Н 1.14 12.70 K 1.982 2.082

All diminsions in mm.



All dimensions in mm

		SPECIFICATION			ION	
ITEM	SYMBOL	MIN.	NOM.	MAX.	TOL.	REMARKS
BODY WIDTH	A1	4.0		4.8		
BODY HEIGHT	A	4.8		5.2		
BODY THICKNESS	Т	3.9		4.2		
PITCH OF COMPONENT	Р		12.7		± 1.0	
FEED HOLE PITCH	Po		12.7		± 0.3	CUMULATIVE PITCH ERROR 1.0 mm/20 PITCH
FEED HOLE CENTRE TO						
COMPONENT CENTRE	P2		6.35		± 0.4	TO BE MEASURED AT BOTTOM OF CLINCH
DISTANCE BETWEEN OUTER					+ 0.6	
LEADS	F		5.08		- 0.2	
COMPONENT ALIGNMENT SIDE VIEW	∆h		0	1.0	0.2	AT TOP OF BODY
COMPONENT ALIGNMENT FRONT VIEW	∆h1		0	1.3		AT TOP OF BODY
TAPE WIDTH	W		18		± 0.5	
HOLD-DOWN TAPE WIDTH	Wo		6		± 0.2	
HOLE POSITION	W1		9		+ 0.7	
					- 0.5	
HOLD-DOWN TAPE POSITION	W2		0.5		± 0.2	
LEAD WIRE CLINCH HEIGHT	Ho		16		± 0.5	
COMPONENT HEIGHT	H1			23.25		
LENGTH OF SNIPPED LEADS	L			11.0		
FEED HOLE DIAMETER	Do		4		± 0.2	
TOTAL TAPE THICKNESS	t			1.2		t1 0.3-0.6
LEAD - TO - LEAD DISTANCE	F1, F2		2.54		+ 0.4	
STAND OFF	H2	0.45		1.45	- 0.1	
CLINCH HEIGHT	H3			3.0		
LEAD PARALLELISM	C1 - C2			0.22		
PULL - OUT FORCE	(P)	6N				

- NOTES

 1. Maximum alignment deviation between leads will not to be greater than 0 2mm.

 2. Maximum non-cumulative variation between tape feed holes shall not exceed 1 mm in 20 pitches.

 3. Holddown tape will not exceed beyond the edge(s) of carrier tape and there shall be no exposure of adhesive.

 4. There will be no more than three (3) consecutive missing components in a tape.

 5. A tape trailier, having at least three feed holes are provided after the last component in a tape.

 6. Splices should not interfere with the sprocket feed holes.

Packing Detail

PACKAGE	STANDARD PACK		INNER CARTO	N BOX	OUTER CARTON BOX		
	Details	Net Weight/Qty	Size	Qty	Size	Qty	Gr Wt
TO-92 Bulk	1K/polybag	200 gm/1K pcs	3" x 7.5" x 7.5"	5K	17" x 15" x 13.5"	80K	23 kgs
TO-92 T&A	2K/ammo box	645 gm/2K pcs	12.5" x 8" x 1.8"	2K	17" x 15" x 13.5"	32K	12.5 kgs

Notes

MPS8598 MPS8599

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Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Discrete Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Discrete Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

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